

TOSHIBA MOS MEMORY PRODUCTS

1,024 WORD × 4 BIT CMOS STATIC RAM
SILICON GATE CMOS

TC5514AP-2/-3

TC5514APL-2/-3

DESCRIPTION

The TC5514AP is a 4,096 bit high speed and low power random access memory organized as 1,024 words by 4 bits using CMOS technology, and operates from a single 5-volt supply.

The 5514AP is compatible with the industry produced NMOS 2114 type 4KRAM, yet offers a more than 90% reduction in power of their NMOS equivalents.

The TC5514AP is a fully CMOS RAM, therefore it is suited for use in low power applications where

battery operation and battery back up for nonvolatility are required. Furthermore the TC5514APL guaranteed a standby current equal to or less than $1\mu\text{A}$ at 60°C ambient temperature is available.

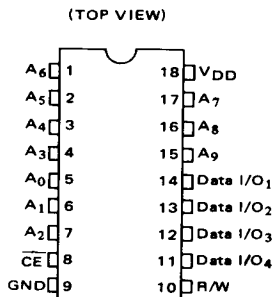
The TC5514AP is guaranteed for data retention at a power supply as low as 2 volts. The TC5514AP is directly TTL compatible in all inputs and outputs.

The TC5514AP is offered in standard 18 pin plastic, 0.3inch in width.

FEATURES

- Standby Current
 - 0.2 μA (Max.) at $T_a=25^\circ\text{C}$
 - 1.0 μA (Max.) at $T_a=60^\circ\text{C}$ } : TC5514APL
 - 20 μA (Max.) } : TC5514AP
- Low Power Dissipation : 15mW (Typ.) operating
- Single 5-volt Supply : $5\text{V} \pm 10\%$
- Data Retention Supply Voltage : 2 ~ 5.5V
- Three State Outputs
- All Inputs and Outputs : Directly TTL Compatible
- Access Time
 - 200ns (Max.) : TC5514 AP/APL-2
 - 300ns (Max.) : TC5514 AP/APL-3
- Fully Static Operation
- On-chip Address Transition Detector
- Fully Compatible with TMM2114AP Family (Nch 2114 type 4KRAM)
- Package
 - Plastic DIP : TC5514AP/APL

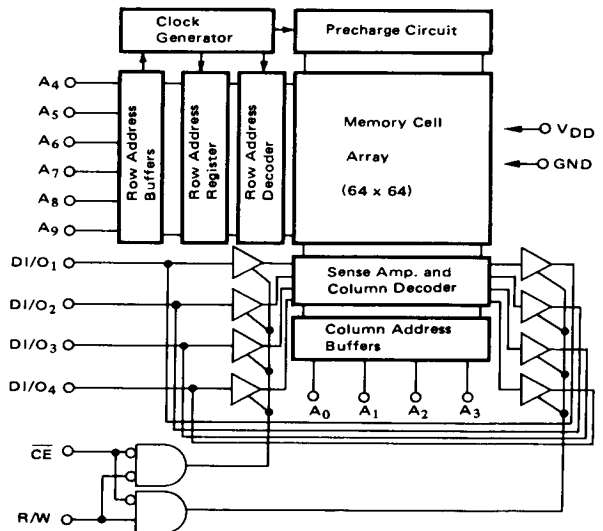
PIN CONNECTION



PIN NAMES

$A_0 \sim A_9$	Address Inputs
R/W	Read Write Control Input
$\overline{\text{CE}}$	Chip Enable Input
Data I/O ₁ ~ ₄	Data Input/Output
V _{DD} /GND	Power Supply Terminals

BLOCK DIAGRAM



TC5514AP-2/-3

TC5514APL-2/-3

MAXIMUM RATINGS

SYMBOL	ITEM	RATING	UNIT
V_{DD}	Power Supply Voltage	-0.3 ~ 7.0	V
V_{IN}	Input Voltage	-0.3 ~ 7.0	V
$V_{I/O}$	I/O Voltage	0 ~ V_{DD}	V
P_D	Power Dissipation ($T_a = 85^\circ\text{C}$)	550	mW
T_{SOLDER}	Soldering Temperature · Time	260 · 10	$^\circ\text{C} \cdot \text{sec}$
T_{STG}	Storage Temperature	-55 ~ 150	$^\circ\text{C}$
T_{OPR}	Operating Temperature	-30 ~ 85	$^\circ\text{C}$

D.C. RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
V_{DD}	Power Supply Voltage	4.5	5.0	5.5	V
V_{IH}	Input High Level Voltage	2.2	—	$V_{DD} + 0.3$	V
V_{IL}	Input Low Level Voltage	-0.3	—	0.8	V
V_{DH}	Data Retention Voltage	2.0	—	5.5	V

D.C. CHARACTERISTICS ($V_{DD} = 5V \pm 10\%$, $T_a = -30 \sim 85^\circ\text{C}$ unless otherwise noted.)

SYMBOL	PARAMETER	CONDITIONS		MIN.	TYP. (1)	MAX.	UNIT	
I_{IL}	Input Leakage Current	$0V \leq V_{IN} \leq V_{DD}$		—	—	± 1.0	μA	
I_{LO}	Output Leakage Current	$\overline{CE} = V_{IH}, 0V \leq V_{I/O} \leq V_{DD}$		—	—	± 1.0	μA	
I_{OH}	Output High Current	$V_{OH} = 2.4V$		-1.0	—	—	mA	
I_{OL}	Output Low Current	$V_{OL} = 0.4V$		2.0	—	—	mA	
I_{DDS}	Standby Current	$V_{DD} = 2V \sim 5.5V$ All Inputs = $0.2V$ or $V_{DD} - 0.2V$	TC5514APL	$T_a = 25^\circ\text{C}$	—	—	0.2	μA
				$T_a = 60^\circ\text{C}$	—	—	1.0	μA
			TC5514AP	—	0.05	20	μA	
I_{DDO1}	Operating Current	$t_{\text{cycle}} = 1\mu\text{s}, I_{OUT} = 0\text{mA}$		—	5.0	9.0	mA	
I_{DDO2}		$t_{\text{cycle}} = 1\mu\text{s}, V_{IH} = V_{DD}, V_{IL} = 0V, I_{OUT} = 0\text{mA}$		—	3.0	5.0		

Note (1): $V_{DD} = 5V, T_a = 25^\circ\text{C}$

CAPACITANCE(2) ($T_a = 25^\circ\text{C}, f = 1\text{MHz}$)

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
C_{IN}	Input Capacitance	$V_{IN} = 0V$	—	4	8	pF
$C_{I/O}$	Input/Output Capacitance	$V_{I/O} = 0V$	—	5	10	pF

Note (2): This parameter is periodically sampled and is not 100% tested.

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A.C. CHARACTERISTICS (V_{DD} = 5V ± 10%, T_a = -30 ~ 85°C)

• READ CYCLE

SYMBOL	PARAMETER	TC5514AP-2/APL-2		TC5514AP-3/APL-3		UNIT
		MIN.	MAX.	MIN.	MAX.	
t _{RC}	Read Cycle Time	200	—	300	—	ns
t _{ACC}	Access Time	—	200	—	300	ns
t _{CO}	\overline{CE} Access Time	—	70	—	100	ns
t _{OH}	Output Data Hold Time	15	—	20	—	ns
t _{DIS}	Output Disable Time	—	60	—	80	ns
t _{COE}	Output Enable Time	5	—	5	—	ns

• WRITE CYCLE

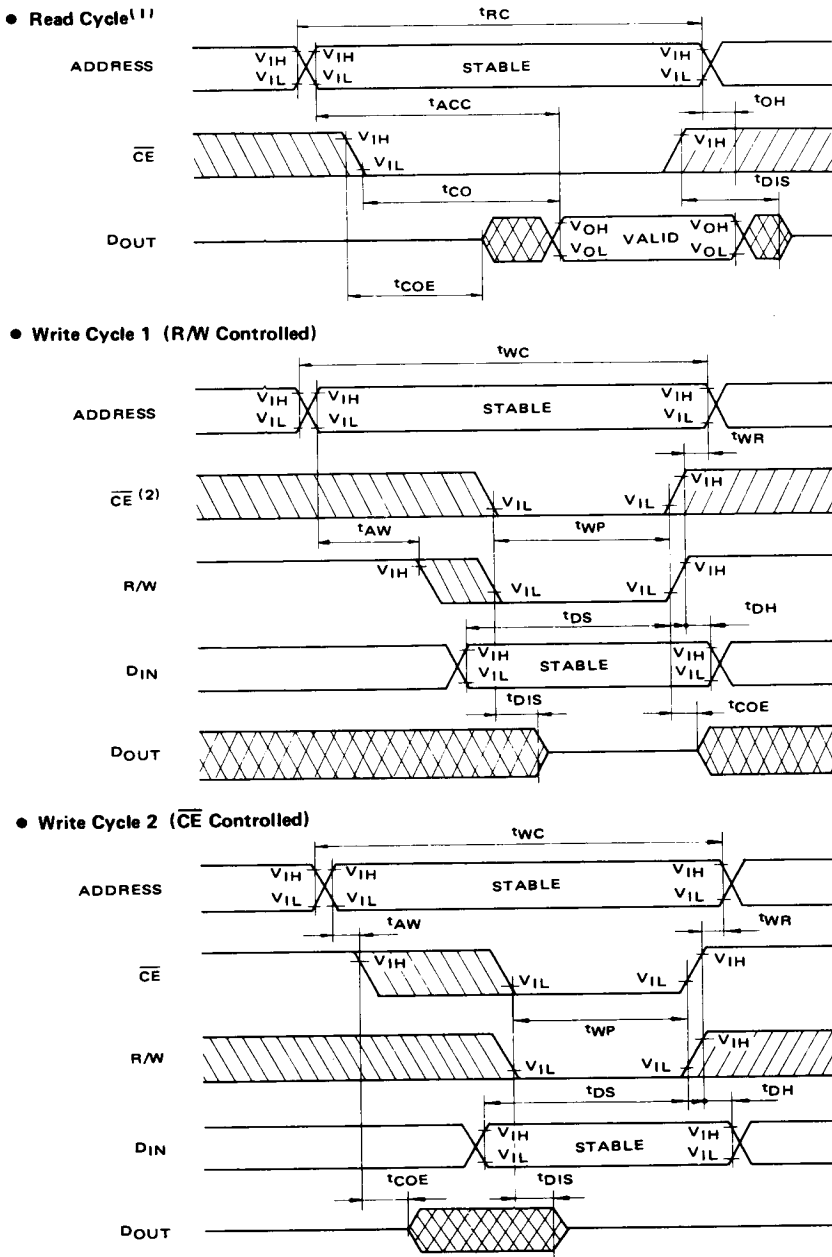
SYMBOL	PARAMETER	TC5514AP-2/APL-2		TC5514AP-3/APL-3		UNIT
		MIN.	MAX.	MIN.	MAX.	
t _{WC}	Write Cycle Time	200	—	300	—	ns
t _{AW}	Address Setup Time	0	—	0	—	ns
t _{WP}	Write Pulse Width	120	—	150	—	ns
t _{DS}	Data Setup Time	120	—	150	—	ns
t _{DH}	Data Hold Time	0	—	0	—	ns
t _{WR}	Write Recovery Time	0	—	0	—	ns

A.C. TEST CONDITIONS

- Output Load : 100 pF + 1 TTL Gate
- Input Pulse Levels : 0.6V, 2.4V
- Timing Measurement Reference Levels
 - Input : 0.8V, 2.2V
 - Output : 0.8V, 2.2V
- Input Pulse Rise and Fall Times : 10 ns

TC5514AP-2/-3 TC5514APL-2/-3

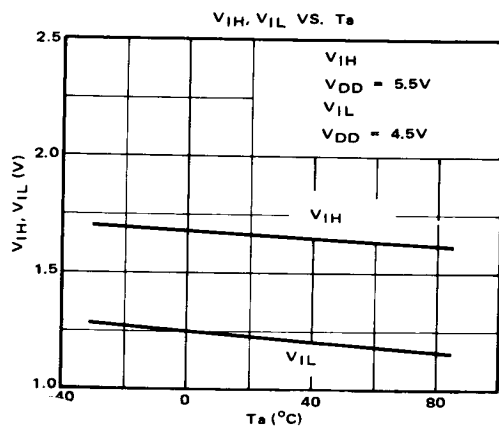
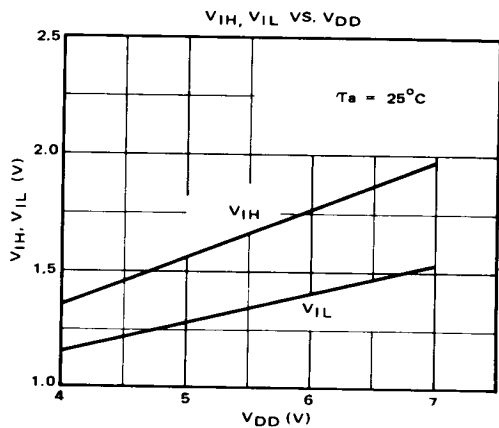
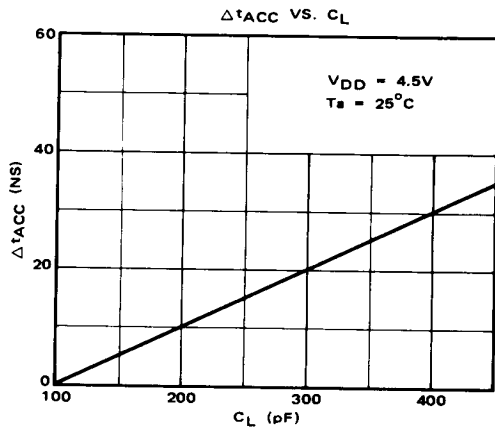
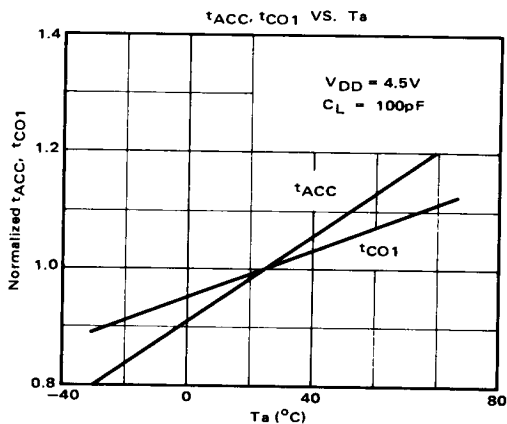
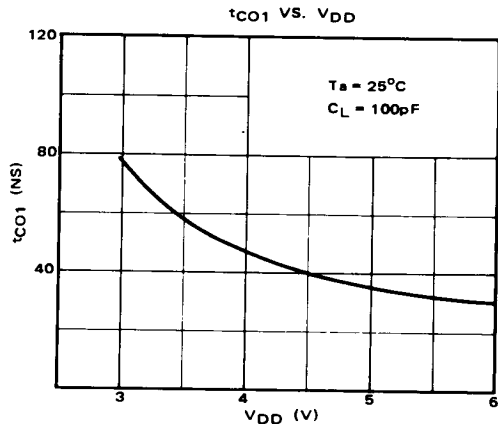
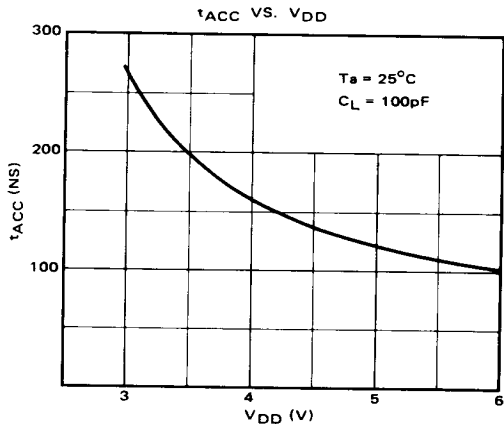
TIMING WAVEFORMS



- Notes: (1) R/W is high for a Read Cycle.
 (2) If the CE low transition occurs simultaneously with the R/W low transition, the output buffers remain in a high impedance state.

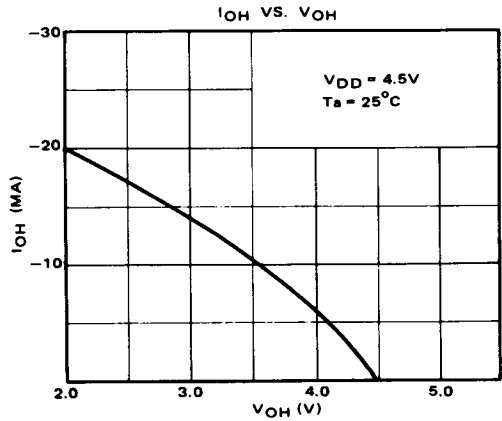
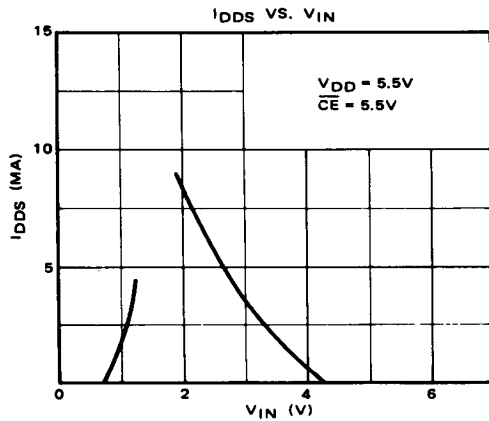
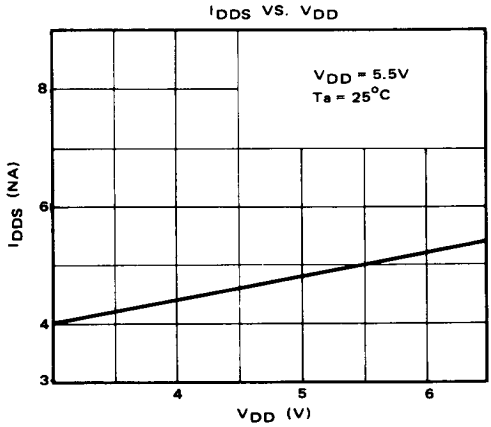
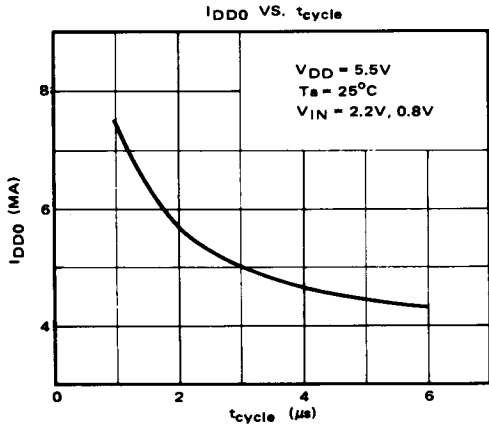
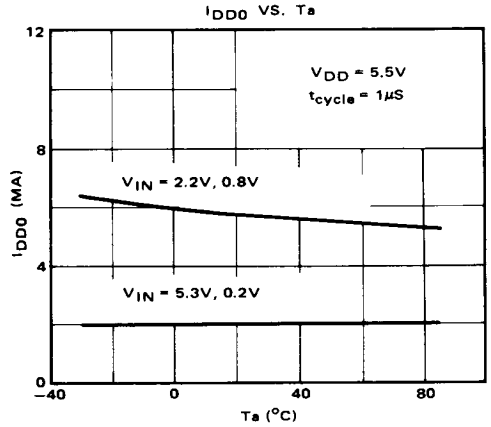
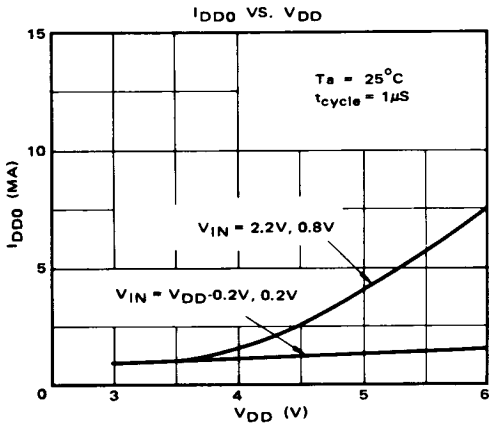
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TC5514APL-2/-3



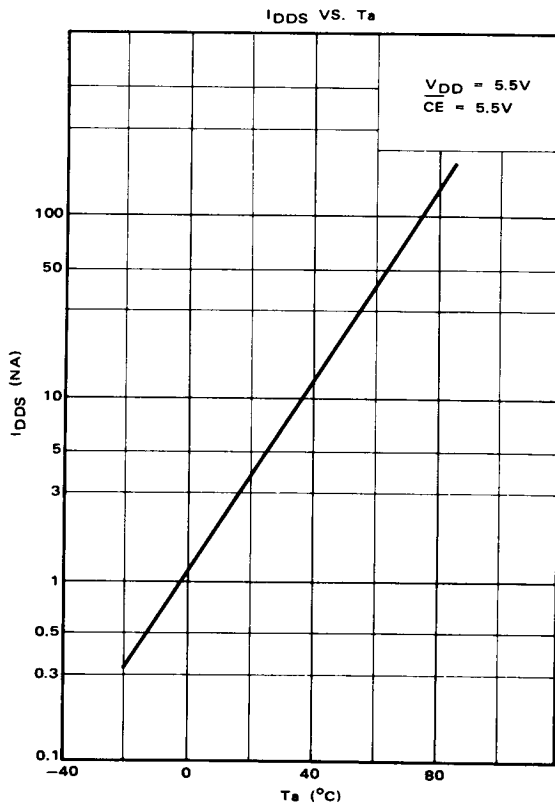
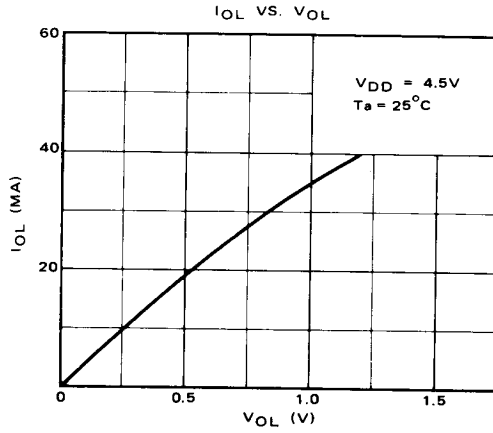
TC5514AP-2/-3

TC5514APL-2/-3



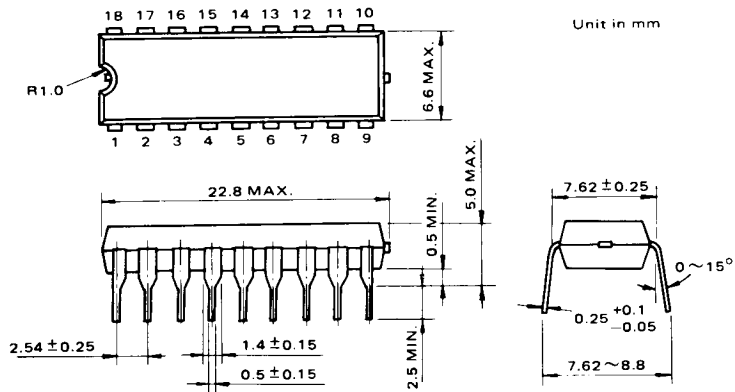
TC5514AP-2/-3

TC5514APL-2/-3



TC5514AP-2/-3 TC5514APL-2/-3

● PLASTIC PACKAGE



Note : Each lead pitch is 2.54mm. All leads are located within 0.25mm of their true longitudinal position with respect to No.1 and No.18 leads.
All dimensions are in millimeters.

Notes: Toshiba does not assume any responsibility for use of any circuitry described; no circuit patent licenses are implied, and Toshiba reserves the right, at any time without notice, to change said circuitry.
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